

2-Input OR Gate with LSTTL-Compatible Inputs

L74VHC1GT32

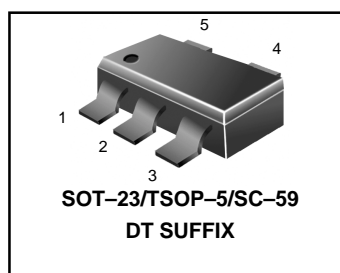
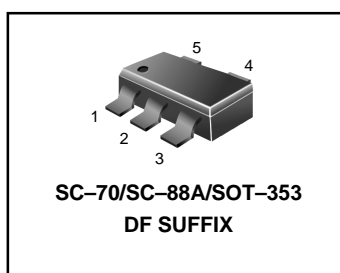
The L74VHC1GT32 is an advanced high speed CMOS 2-input OR gate fabricated with silicon gate CMOS technology. It achieves high speed operation similar to equivalent Bipolar Shortly TTL while maintaining CMOS low power dissipation.

The internal circuit is composed of three stages, including an open drain output which provides the ability to set output switching level. This allows the L74VHC1GT32 to be used to interface 5 V circuits to circuits of any voltage between V_{CC} and 7 V using an external resistor and power supply.

The device input is compatible with TTL-type input thresholds and the output has a full 5.0 V CMOS level output swing. The input protection circuitry on this device allows overvoltage tolerance on the input, allowing the device to be used as a logic-level translator from 3.0 V CMOS logic to 5.0 V CMOS Logic or from 1.8 V CMOS logic to 3.0 V CMOS Logic while operating at the high-voltage power supply.

The L74VHC1GT32 input structure provides protection when voltages up to 7 V are applied, regardless of the supply voltage. This allows the L74VHC1GT32 to be used to interface 5 V circuits to 3 V circuits. The output structures also provide protection when $V_{CC} = 0$ V. These input and output structures help prevent device destruction caused by supply voltage – input/output voltage mismatch, battery backup, hot insertion, etc.

- High Speed: $t_{PD} = 3.7$ ns (Typ) at $V_{CC} = 5$ V
- Low Power Dissipation: $I_{CC} = 2$ mA (Max) at $T_A = 25^\circ\text{C}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Pin and Function Compatible with Other Standard Logic Families
- Chip Complexity: FETs = 60; Equivalent Gates = 15



| PIN ASSIGNMENT | |
|----------------|----------|
| 1 | IN B |
| 2 | IN A |
| 3 | GND |
| 4 | OUT Y |
| 5 | V_{CC} |

MARKING DIAGRAMS

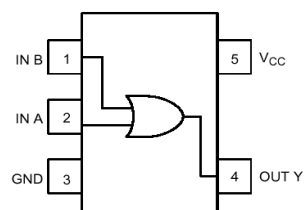
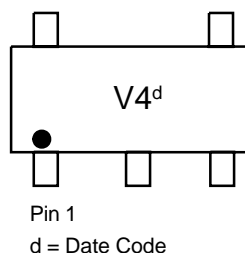
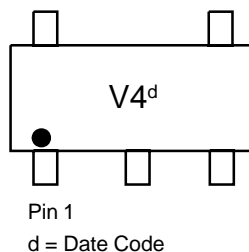


Figure 1. Pinout (Top View)

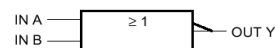


Figure 2. Logic Symbol

FUNCTION TABLE

| Inputs | | Output |
|--------|---|--------|
| A | B | Y |
| L | L | L |
| L | H | H |
| H | L | H |
| H | H | H |

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

L74VHC1GT32

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|-----------------------|--|--|---|
| V _{CC} | DC Supply Voltage | - 0.5 to + 7.0 | V |
| V _{IN} | DC Input Voltage | - 0.5 to 7.0 | V |
| V _{OUT} | DC Output Voltage | V _{CC} =0 High or Low State | - 0.5 to 7.0 -0.5 to V _{CC} + 0.5 |
| I _{IK} | Input Diode Current | -20 | mA |
| I _{OK} | Output Diode Current | V _{OUT} < GND; V _{OUT} > V _{CC} | +20 mA |
| I _{OUT} | DC Output Current, per Pin | + 25 | mA |
| I _{CC} | DC Supply Current, V _{CC} and GND | +50 | mA |
| P _D | Power dissipation in still air | SC-88A, TSOP-5 | 200 mW |
| θ _{JA} | Thermal resistance | SC-88A, TSOP-5 | 333 °C/W |
| T _L | Lead Temperature, 1 mm from Case for 10 s | 260 | °C |
| T _J | Junction Temperature Under Bias | + 150 | °C |
| T _{stg} | Storage temperature | -65 to +150 | °C |
| V _{ESD} | ESD Withstand Voltage | Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4) | >2000 > 200 N/A V |
| I _{LATCH-UP} | Latch-Up Performance | Above V _{CC} and Below GND at 125°C (Note 5) | ± 500 mA |

1. Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.
2. Tested to EIA/JESD22-A114-A
3. Tested to EIA/JESD22-A115-A
4. Tested to JESD22-C101-A
5. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|---------------------------------|-----------------------------|--|-----------------|------|
| V _{CC} | DC Supply Voltage | 2.0 | 5.5 | V |
| V _{IN} | DC Input Voltage | 0.0 | 5.5 | V |
| V _{OUT} | DC Output Voltage | 0.0 | V _{CC} | V |
| T _A | Operating Temperature Range | - 55 | + 125 | °C |
| t _r , t _f | Input Rise and Fall Time | V _{CC} = 3.3 ± 0.3 V V _{CC} = 5.0 ± 0.5 V | 0 100 20 | ns/V |

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

| Junction Temperature °C | Time, Hours | Time, Years |
|-------------------------|-------------|-------------|
| 80 | 1,032,200 | 117.8 |
| 90 | 419,300 | 47.9 |
| 100 | 178,700 | 20.4 |
| 110 | 79,600 | 9.4 |
| 120 | 37,000 | 4.2 |
| 130 | 17,800 | 2.0 |
| 140 | 8,900 | 1.0 |

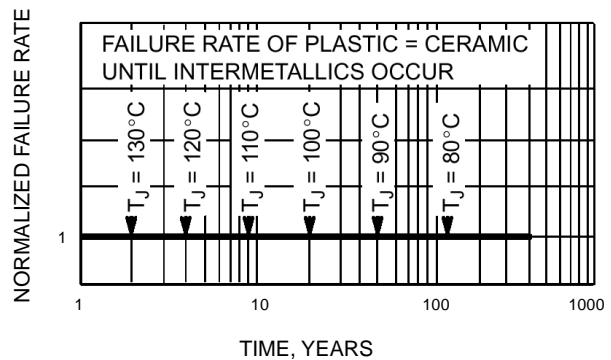


Figure 3. Failure Rate vs. Time Junction Temperature

L74VHC1GT32
DC ELECTRICAL CHARACTERISTICS

| Symbol | Parameter | Test Conditions | V _{CC} (V) | T _A = 25°C | | | T _A ≤ 85°C | | -55°C ≤ T _A ≤ 125°C | | Unit |
|-----------------|---|--|------------------------|-----------------------|-------------------|--------------------|-----------------------|--------------------|--------------------------------|-----|------|
| | | | | Min | Typ | Max | Min | Max | Min | Max | |
| V _{IH} | Minimum High-Level Input Voltage | | 3.0 4.5 5.5 | 1.4 2.0 2.0 | | | 1.4 2.0 2.0 | | 1.4 2.0 2.0 | V | |
| V _{IL} | Maximum Low-Level Input Voltage | | 3.00 4.5 5.5 | | | 0.53 0.8 0.8 | | 0.53 0.8 0.8 | 0.53 0.8 0.8 | V | |
| V _{OH} | Minimum High-Level Output Voltage V _{IN} = V _{IH} or V _{IL} | V _{IN} = V _{IH} or V _{IL} I _{OH} = -50 μA | 2.0 3.0 4.5 | 1.9 2.9 4.4 | 2.0 3.0 4.0 | | 1.9 2.9 4.4 | | 1.9 2.9 4.4 | V | |
| | | V _{IN} = V _{IH} or V _{IL} I _{OH} = -4 mA I _{OH} = -8 mA | 3.0 4.5 | 2.58 3.94 | | | 2.48 3.80 | | 2.34 3.66 | | |
| V _{OL} | Maximum Low-Level Output Voltage V _{IN} = V _{IH} or V _{IL} | V _{IN} = V _{IH} or V _{IL} I _{OL} = 50 μA | 2.0 3.0 4.5 | | 0.0 0.0 0.0 | 0.1 0.1 0.1 | | 0.1 0.1 0.1 | 0.1 0.1 0.1 | V | |
| | | V _{IN} = V _{IH} or V _{IL} I _{OL} = 4 mA I _{OL} = 8 mA | 3.0 4.5 | | | 0.36 0.36 | | 0.44 0.44 | 0.52 0.52 | | |
| I _{IN} | Maximum Input Leakage Current | V _{IN} = 5.5 V or GND | 0 to 5.5 | | | ±0.1 | | ±1.0 | ±1.0 | μA | |
| I _{CC} | Maximum Quiescent Supply Current | V _{IN} = V _{CC} or GND | 5.5 | | | 2.0 | | 20 | 40 | μA | |
| | | | | | | | | | | | |

AC ELECTRICAL CHARACTERISTICS C_{load} = 50 pF, Input t_r = t_f = 3.0 ns

| Symbol | Parameter | Test Conditions | T _A = 25°C | | | T _A ≤ 85°C | | -55°C ≤ T _A ≤ 125°C | | Unit |
|--|--|--|---|------------|-------------|-----------------------|-------------|--------------------------------|--------------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| t _{PLH} , t _{PHL} | Maximum Propagation Delay, Input A or B to Y | V _{CC} = 3.3 ± 0.3 V C _L = 15 pF C _L = 50 pF | | 4.8 6.1 | 7.9 11.4 | | 9.5 13.0 | | 11.5 15.5 | ns |
| | | V _{CC} = 5.0 ± 0.5 V C _L = 15 pF C _L = 50 pF | | 3.7 4.4 | 5.5 7.5 | | 6.5 8.5 | | 8.0 10.0 | |
| C _{IN} | Maximum Input Capacitance | | | 5.5 | 10 | | 10 | | 10 | pF |
| | | | Typical @ 25°C, V_{CC} = 5.0 V | | | | | | | |
| C _{PD} | Power Dissipation Capacitance (Note 6) | | | 11 | | | | | pF | |

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

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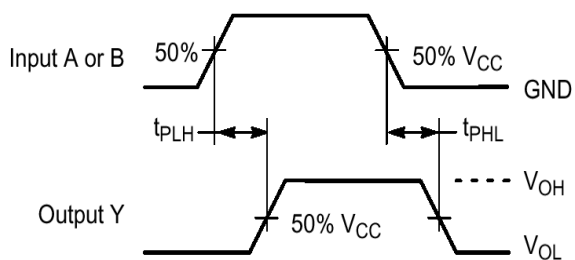
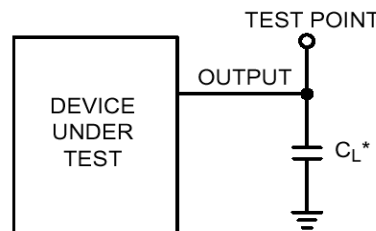


Figure 4. Switching Waveforms



*Includes all probe and jig capacitance

Figure 5. Test Circuit

DEVICE ORDERING INFORMATION

| Device Order Number | Device Nomenclature | | | | | | Package Type (Name/SOT#/ Common Name) | Tape and Reel Size |
|---------------------|---------------------|-----------------------|------------|-----------------|----------------|--------------------|--|-------------------------------|
| | Circuit Indicator | Temp Range Identifier | Technology | Device Function | Package Suffix | Tape & Reel Suffix | | |
| L74VHC1GT32DFT1 | L | 74 | VHC1G | T32 | DF | T1 | SC-70/SC-88A/ SOT-353 | 178 mm (7 in) 3000 Unit |
| L74VHC1GT32DFT2 | L | 74 | VHC1G | T32 | DF | T2 | SC-70/SC-88A/ SOT-353 | 178 mm (7 in) 3000 Unit |
| L74VHC1GT32DFT4 | L | 74 | VHC1G | T32 | DF | T4 | SC-70/SC-88A/ SOT-353 | 330 mm (13 in) 10,000 Unit |
| L74VHC1GT32DTT1 | L | 74 | VHC1G | T32 | DT | T1 | SOT-23/TSOPS/ SC-59 | 178 mm (7 in) 3000 Unit |
| L74VHC1GT32DTT3 | L | 74 | VHC1G | T32 | DT | T3 | SOT-23/TSOPS/ SC-59 | 330 mm (13 in) 10,000 Unit |

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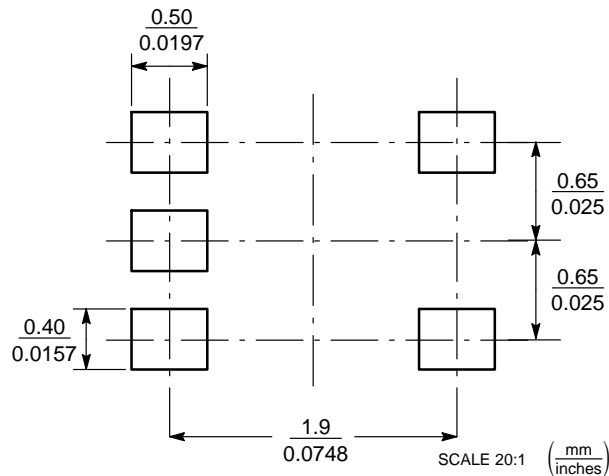
PACKAGE DIMENSIONS SC70-5/SC-88A/SOT-353 DF SUFFIX



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|------|
| | MIN | MAX | MIN | MAX |
| A | 0.071 | 0.087 | 1.80 | 2.20 |
| B | 0.045 | 0.053 | 1.15 | 1.35 |
| C | 0.031 | 0.043 | 0.80 | 1.10 |
| D | 0.004 | 0.012 | 0.10 | 0.30 |
| G | 0.026 BSC | | 0.65 BSC | |
| H | --- | 0.004 | --- | 0.10 |
| J | 0.004 | 0.010 | 0.10 | 0.25 |
| K | 0.004 | 0.012 | 0.10 | 0.30 |
| N | 0.008 REF | | 0.20 REF | |
| S | 0.079 | 0.087 | 2.00 | 2.20 |

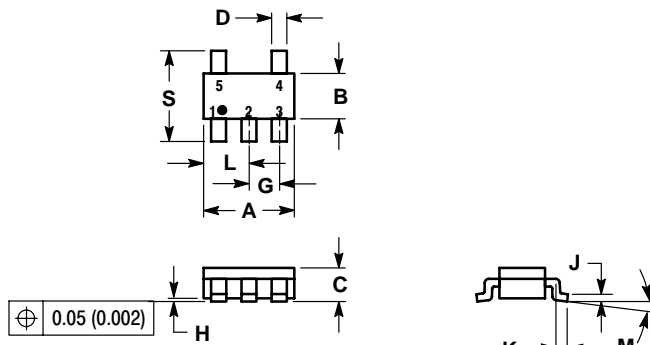
SOLDERING FOOTPRINT*



L74VHC1GT32

PACKAGE DIMENSIONS

SOT23-5/TSOP-5/SC59-5
DT SUFFIX



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. A AND B DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|-------|--------|--------|
| | MIN | MAX | MIN | MAX |
| A | 2.90 | 3.10 | 0.1142 | 0.1220 |
| B | 1.30 | 1.70 | 0.0512 | 0.0669 |
| C | 0.90 | 1.10 | 0.0354 | 0.0433 |
| D | 0.25 | 0.50 | 0.0098 | 0.0197 |
| G | 0.85 | 1.05 | 0.0335 | 0.0413 |
| H | 0.013 | 0.100 | 0.0005 | 0.0040 |
| J | 0.10 | 0.26 | 0.0040 | 0.0102 |
| K | 0.20 | 0.60 | 0.0079 | 0.0236 |
| L | 1.25 | 1.55 | 0.0493 | 0.0610 |
| M | 0 | 10 | 0 | 10 |
| S | 2.50 | 3.00 | 0.0985 | 0.1181 |

SOLDERING FOOTPRINT*

